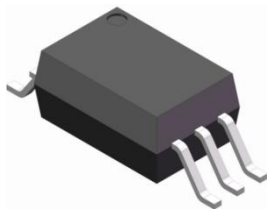
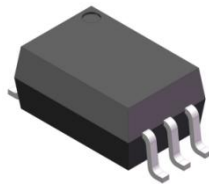
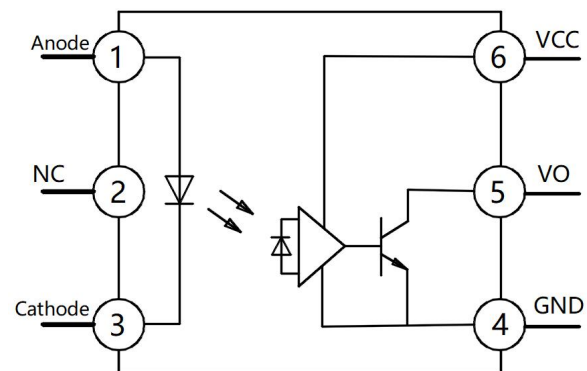


Product packaging logic diagram

SOP6-W



SOP6-P

**Features**

- Very high speed: 10MBit/s
- High isolation voltage between input and output ($V_{iso} = 5000V$ rms)
- Operating Temperature: $-40^{\circ}C \sim 85^{\circ}C$
- Environmentally friendly products, compliant with CQC, UL, and VDE requirements

Mechanical Data

- Case: SOP6-W, SOP6-P
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solder ability-per MIL-STD-202, Method 208

Applications

- Fiber optic communication, photoelectric conversion, and digital signal processing are widely used. Can improve data transmission speed and reliability
- In motor control, PLC systems, and industrial robots, Achieve precise control through microsecond-level response and enhance system stability.
- Relying on high-speed optocouplers to achieve real-time data transmission and electrical isolation, ensuring patient safety and data accuracy. Medical imaging equipment and vital signs monitors.
- Spacecraft, satellite communications and radar systems, High-speed digital signal transmission, whose anti-interference capability is crucial in complex environments
- Power system monitoring, frequency converters and renewable energy converters, Ensure the safe operation of equipment.
- In-vehicle entertainment system, BMS (Battery Management System), Improve audio quality and circuit safety.



Ordering Information

<u>XL</u>	<u>6XX</u>	<u>(M)</u>	<u>(G)</u>	<u>(X)</u>	-	<u>(U)</u>	<u>(N)</u>	<u>(Y)</u>
①	②	③	④	⑤		⑥	⑦	⑧

- ① Brand (XL)
- ② Product series (600, 601, 611)
- ③ Package type(SOP6-P:P; SOP6-W:W)
- ④ Halogen option (None : Halogen free)
- ⑤ CTR Bank(None)
- ⑥ Lead frame (None: Copper)
- ⑦ Customer option 1 (0-9 or A- Z or none)
- ⑧ Customer option 2 (0-9 or A- Z or none)

Part Number	Package	Shipping Quantity	Marking Code
XL601P	SOP6-P	1000pcs / Tape & Reel	XL601

Marking Information

- " XL" denotes brand
- " XX" denotes Product series: 00, 01, 11.
- " Y" denotes Year : A(2024), B(2025), C(2026)
- " WW" denotes Week' s number
- " N" denotes the day of Week.



Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Emitter	Forward Current	I _F	50	mA
	Reverse Voltage	V _R	5	V
	Power Dissipation	P _D	100	mW
Detector	Collector Output	P _O	85	mW
	Output Current	I _O	50	mA
	Supply Voltage	V _{CC}	7	V
	Output Voltage	V _O	7	V

Thermal Characteristics

Parameter	Symbol	Value	Unit
Isolation Voltage *2	V _{ISO}	5000	Vrms
Operating Temperature	T _{OPR}	-40 ~ +85	°C
Storage Temperature Range	T _{STG}	-55 ~ +125	°C
Soldering Temperature *3	T _{SOL}	260	°C

Notes:

1. 40 to 60% RH, AC for 1 minute
2. For 10 seconds

Electrical Characteristics (@ T_A = 25°C unless otherwise specified)

Parameter		Symbol	Test Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V _F	I _F = 10mA	-	1.33	1.8	V
	Reverse Breakdown Voltage	B _{VR}	I _R =10μA	5	20	45	V
	Capacitance	C _{in}	V _R = 0V, f = 1kHz	-	70	-	pF
	Diode Temperature Coefficient	ΔV _F /ΔT _A	I _F =10mA	-	-1.9	-	mV/°C
Output	High Level Supply Current	I _{CCH}	V _{CC} =5.5V, I _F =0mA	-	6.0	9	mA
	Low Level Supply Current	I _{ACL}	V _{CC} =5.5V, I _F =10mA	-	7.5	10	mA
Transfer Characteristics	High Level Output Current	I _{OH}	V _{CC} =5.5V V _O =5.5V I _F = 250μA	-	2.1	30	μA
	Low Level Output Voltage	V _{OL}	V _{CC} =5.5V I _F =5mA I _{OL} =13mA	-	0.4	0.6	V
	Input Threshold Current	I _{FT}	V _{CC} =5.5V V _O =0.6V I _{OL} =13mA	-	2.4	5	mA
	Isolation Resistance	R _{IO}	V _{IO} = 500Vdc 40~60% R.H.	-	1×10 ¹²	-	Ω
	Floating Capacitance	C _{IO}	f = 1MHz	-	0.6	-	pF

Switching Characteristics (@ $T_A = -40^{\circ}\text{C} \sim 85^{\circ}\text{C}$, $V_{CC} = 5\text{V}$, $I_F = 7.5\text{mA}$, unless otherwise specified)

Parameter		Symbol	Test Condition	Min.	Typ.	Max.	Unit
Propagation Delay Time to Output HIGH Level		T_{PLH}	$C_L = 15\text{pF}$ $R_L = 350\Omega$ $T_A = 25^{\circ}\text{C}$	-	41	100	ns
Propagation Delay Time to Output Low Level		T_{PHL}		-	50	100	ns
Pulse Width Distortion		$ T_{PHL} - T_{PLH} $		-	9	35	ns
Output Rise Time (10–90%)		t_r		-	40	-	ns
Output Rise Time (90–10%)		t_f		-	10	-	ns
Propagation Delay Skew		t_{psk}		-	-	40	ns
Common Mode Transient Immunity(at Logic High)	600	$ CM_H $	$T_A = 25^{\circ}\text{C}, I_F = 0\text{mA}$ $ V_{CM} = 10\text{V(Peak)}$ $V_{OH} = 2.0\text{V}, R_L = 350\Omega$	-	-	-	V/ μs
	601		$T_A = 25^{\circ}\text{C}, I_F = 0\text{mA}$ $ V_{CM} = 50\text{V(Peak)}$ $V_{OH} = 2.0\text{V}, R_L = 350\Omega$	5000	-	-	
	611		$T_A = 25^{\circ}\text{C}, I_F = 0\text{mA}$ $ V_{CM} = 1000\text{V(Peak)}$ $V_{OH} = 2.0\text{V}, R_L = 350\Omega$	20000	-	-	
Common Mode Transient Immunity (at Logic Low)	600	$ CM_L $	$I_F = 7.5\text{mA}, V_{OL} = 0.8\text{V}$ $R_L = 350\Omega, T_A = 25^{\circ}\text{C}$ $ V_{CM} = 10\text{V(Peak)}$	-	-	-	V/ μs
	601		$I_F = 7.5\text{mA}, V_{OL} = 0.8\text{V}$ $R_L = 350\Omega, T_A = 25^{\circ}\text{C}$ $ V_{CM} = 50\text{V(Peak)}$	5000	-	-	
	611		$I_F = 7.5\text{mA}, V_{OL} = 0.8\text{V}$ $R_L = 350\Omega, T_A = 25^{\circ}\text{C}$ $ V_{CM} = 1000\text{V(Peak)}$	20000	-	-	

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Fig.1 Forward Current vs. Forward Voltage

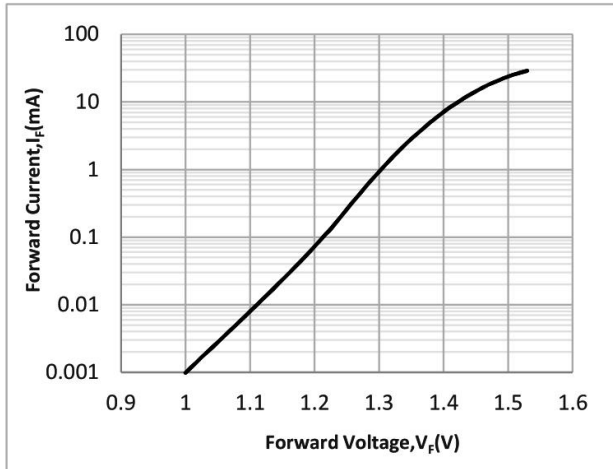


Fig.2 Low Level Output Voltage vs. Ambient Temperature

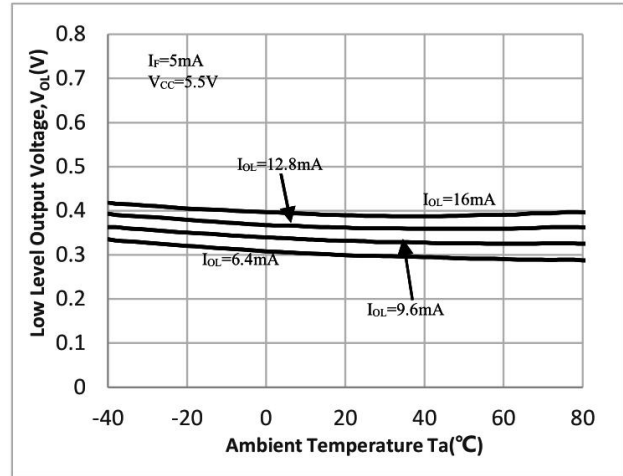


Fig.3 Switching time vs. Forward Current

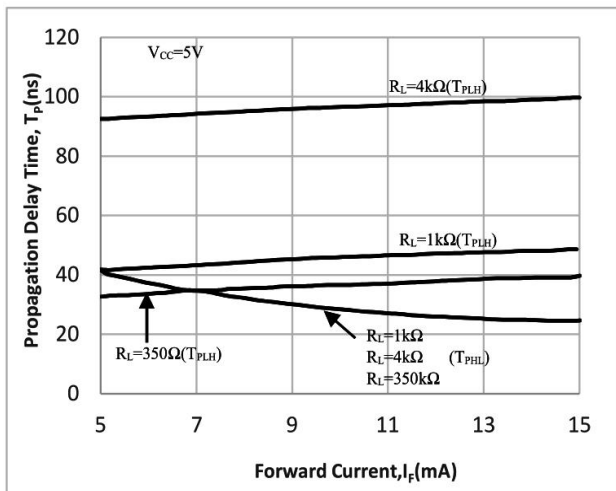


Fig.4 Low Level Output Current vs. Ambient Temperature

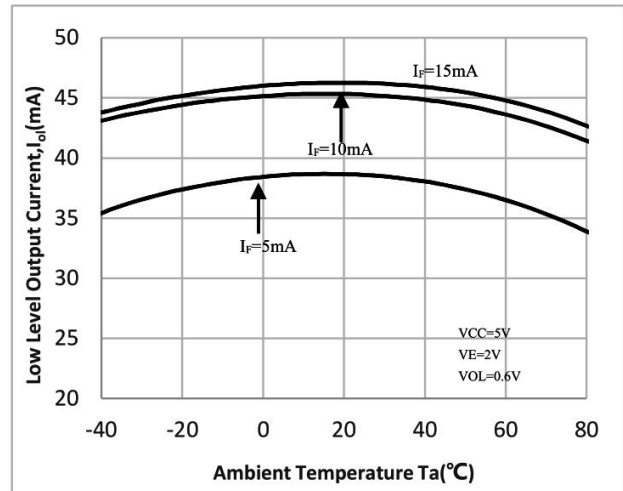


Fig.5 Start Current vs. Ambient Temperature

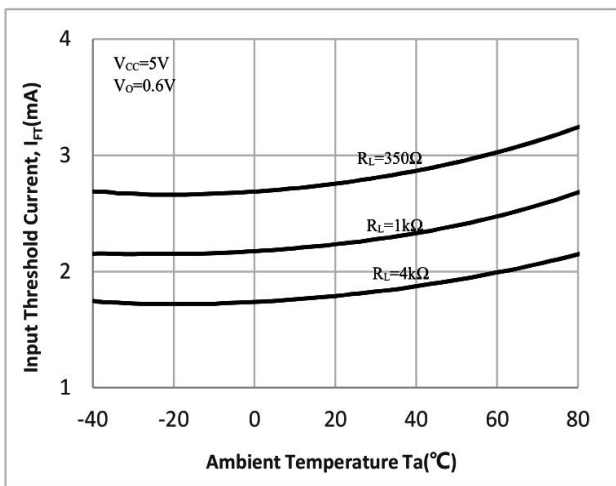
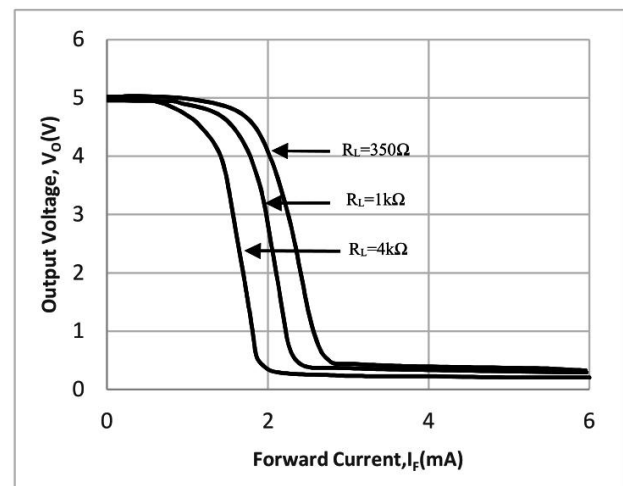


Fig.6 Output Voltage vs. Input Forward Current



Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Fig.7 Pulse Width Distortion vs. Ambient Temperature

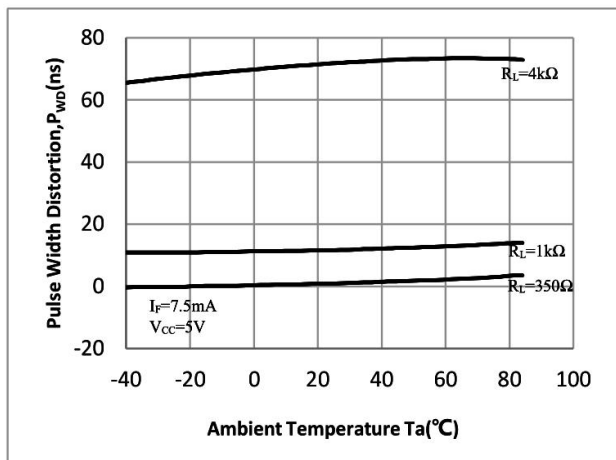


Fig.8 Rise and Fall Time vs. Ambient Temperature

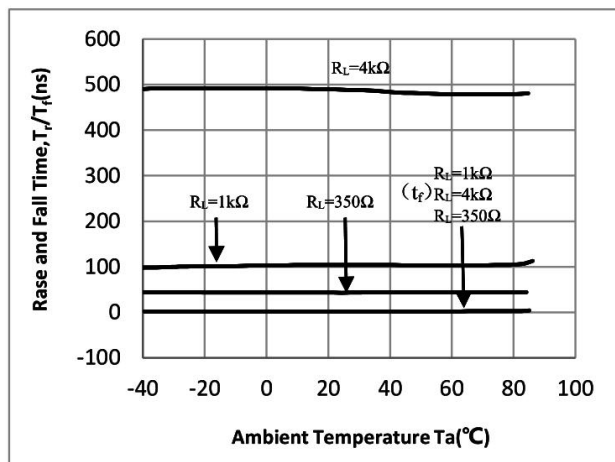


Fig.9 Test Circuit and Waveforms for t_{PLH} , t_{PHL} , t_r and t_f

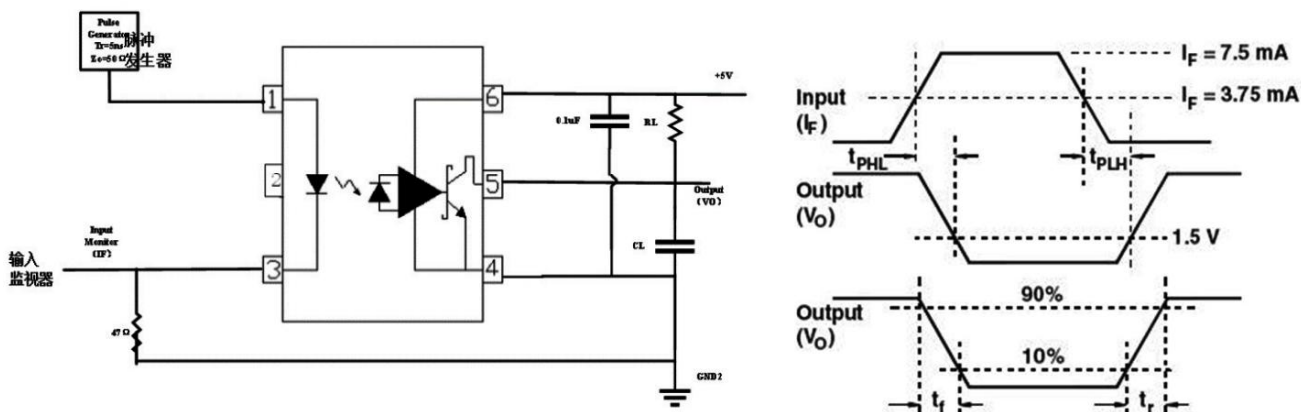
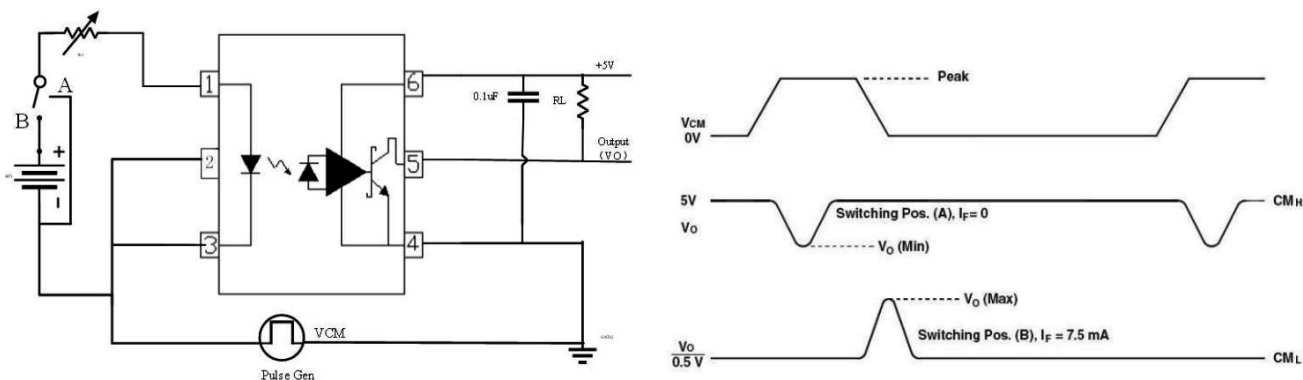
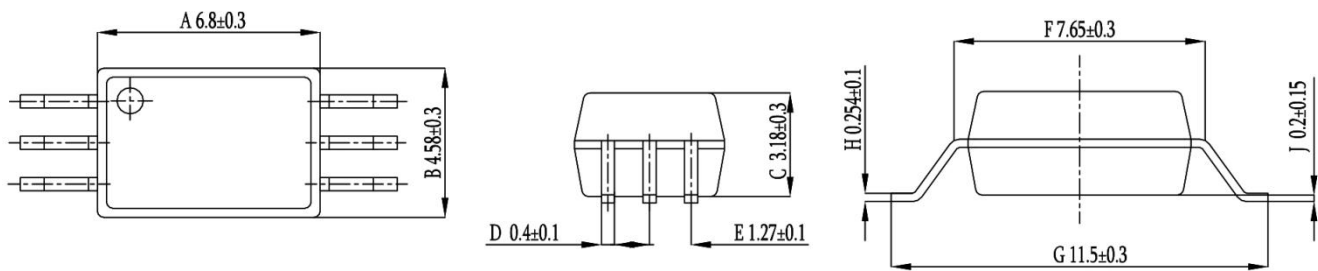


Fig.10 Test Circuit Common Mode Transient Immunity

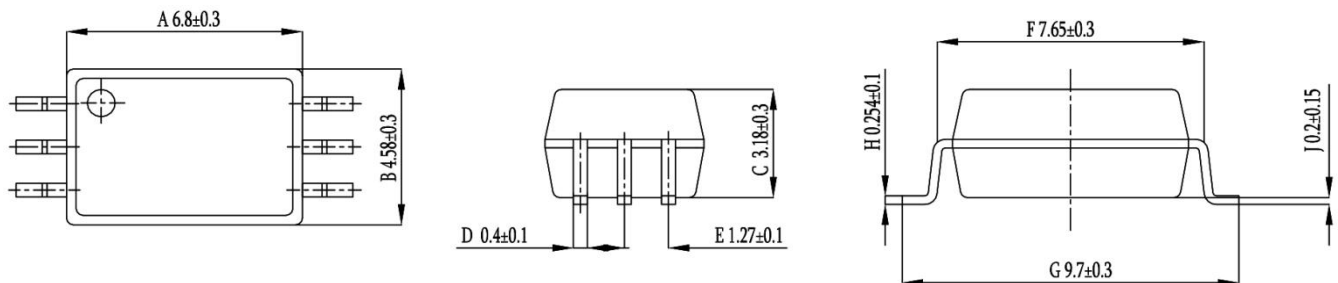


Package Outline Dimensions (unit: mm)

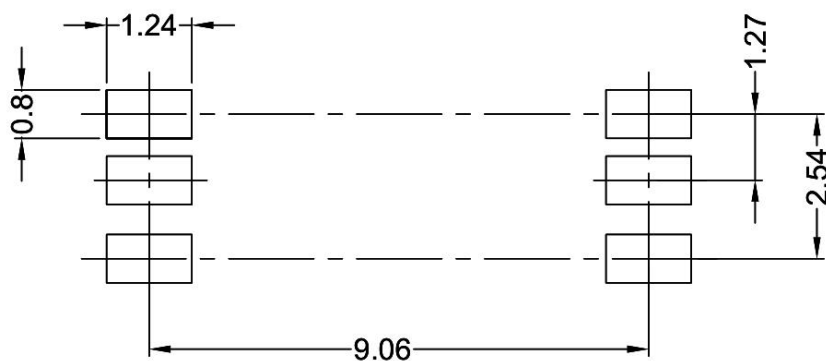
SOP6-W



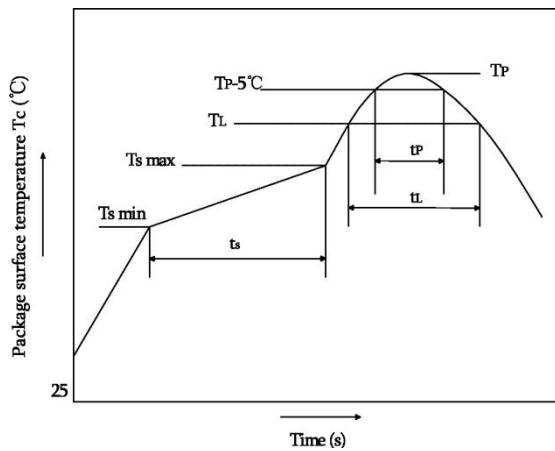
SOP6-P



SOLDERING FOOTPRINT (unit: mm)



Reflow soldering

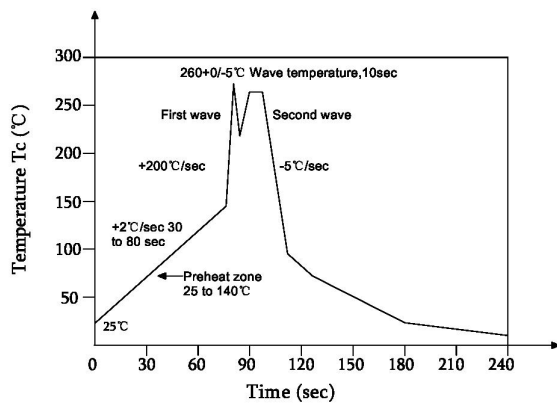


	Symbol	Min	Max	Unit
Preheat temperature	T_s	150	200	$^\circ\text{C}$
Preheat time	t_s	60	120	s
Ramp-up rate(T_L to T_P)			3	$^\circ\text{C/s}$
Liquidus temperature	T_L	217		$^\circ\text{C}$
Time above T_L	t_L	60	150	s
Peak temperature	T_P		260	$^\circ\text{C}$
Time during which T_c is between ($T_P - 5$) and T_P	t_p		30	s
Ramp-down rate(T_P to T_L)			6	$^\circ\text{C/s}$

Note:

Reflow soldering is recommended at the temperatures and times shown, no more than three times.

Wave soldering



Profile feature	
Average ramp-up rate	$\sim 200^\circ\text{C/s}$
Heating rate during preheat	1°C/s to 2°C/s typical; 4°C/s maximum
Final preheat temperature T_s	$\sim 130^\circ\text{C}$
Preheat time (25°C to T_s)	$> 60\text{s}$
Peak temperature T_P	260°C
Time within peak temperature t_p	10s
Ramp-down rate	5°C/s maximum

Soldering with hand soldering iron

- Hand soldering iron is only used for product rework or sample testing.
- Hand soldering iron requirements: Temperature: $360^\circ\text{C} \pm 5^\circ\text{C}$ within 3s.

Packing

Package Type	Packing Form	Quantity per Tube & Reel	Quantity per Box	Quantity per Carton	Antistatic Bag Specification	Box Specification	Carton Specification	Note
SOP6	Reel($\phi 330$ mm)	1000 pcs/reel	2 reels /box	5 boxes /ctn	380*420mm	350*340*60mm	365*330*370mm	Guard band 200mm/min.

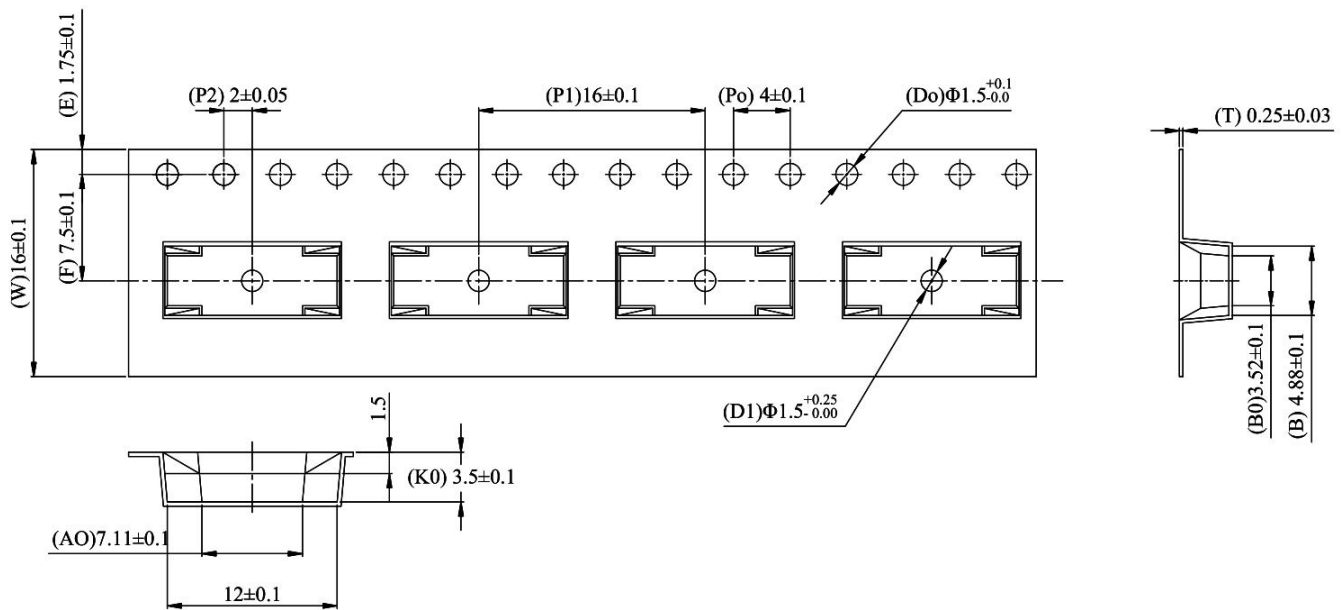
■ Summary table

■ SOP6 (Reel)

Qty/reel: 1000pcs. Qty/box: 2000pcs.

Qty/ctn : 10000pcs.

Schematic: (unit:mm)



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